APPLICATION DATA SHEET

INVENTOR INFORMATION

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Citizenship Country: **JAPAN**

CORRESPONDENCE INFORMATION

Correspondence customer number: 23911

APPLICATION INFORMATION

Title line one:
Title line two:

Title line three:

Title line four:

Total drawing sheets: Formal drawings?: Application type: Docket Number: SEMICONDUCTOR WAFER AND APPARATUS OF PROCESS FOR FABRICATING SEMICONDUCTOR DEVICES

11 Yes Utility

155/50674

REPRESENTATIVE INFORMATION

Representative customer number:

23911

CONTINUITY INFORMATION

This application is a:

Application one:

Filing date:

Patent number:

371 of

PCT/JP01/03635 April 26, 2001

PRIOR FOREIGN APPLICATIONS

Foreign application one:

2000-128502 April 27, 2000

Filing date: Country:

Japan

Priority claimed:

Yes